



TET ESTEL AS
ESTONIA

**June
2013**

**Series
TFI393-2500**

Low switching losses

Low reverse recovery charge

Distributed amplified gate for high di/dt

**High Frequency Inverter grade
Capsule Thyristor
Type TFI393-2500**

Low switching losses
Low reverse recovery charge
Distributed amplified gate for high di/dt

Maximum mean on-state current	I_{TAV}	2500 A
Maximum repetitive peak off-state and reverse voltage	U_{DRM}	2200 ÷ 2800 V
Turn-off time	t_q	63; 80; 100 μs
U _{DRM} , U _{RRM} , V	2200	2400
Voltage code	22	24
Tvj, °C		- 60 ÷ 125

MAXIMUM ALLOWABLE RATINGS

Symbols and parameters		Units	TFI393-2500	Conditions
I _{TAV}	Mean on-state current	A	2500 4010	Tc=88 °C, Tc=55 °C, 180° half-sine wave, 50 Hz
I _{TRMS}	RMS on-state current	A	3925	Tc=88 °C
I _{TSM}	Surge on-state current	kA	66 70	Tvj=125°C Tvj=25°C
I ² t	Limiting load integral	kA ² s	21780 24500	Tvj=125°C Tvj=25°C
U _{DRM} , U _{RRM}	Repetitive peak off-state and reverse voltage	V	2200÷2800	Tj min≤Tvj≤TjM 180° half-sine wave, 50 Hz Gate open
U _{DSM} , U _{RSR}	Non-repetitive peak off-state and reverse voltage	V	2300÷2900	Tj min≤Tvj≤TjM 180° half-sine wave tp=10 ms, Single pulse Gate open
(di/dt) crit	Critical rate of rise of on-state current : non - repetitive repetitive	A/μs	1600 800	Tvj=125°C ; Ud=0,67 U _{DRM} , Gate pulse : 10V, 5 Ω, 1 μs rise time, 10 μs
U _{RG}	Peak reverse gate voltage	V	5	Tj min≤Tvj≤TjM
T _{stg}	Storage temperature	°C	-60÷80	
Tvj	Junction temperature	°C	-60÷125	

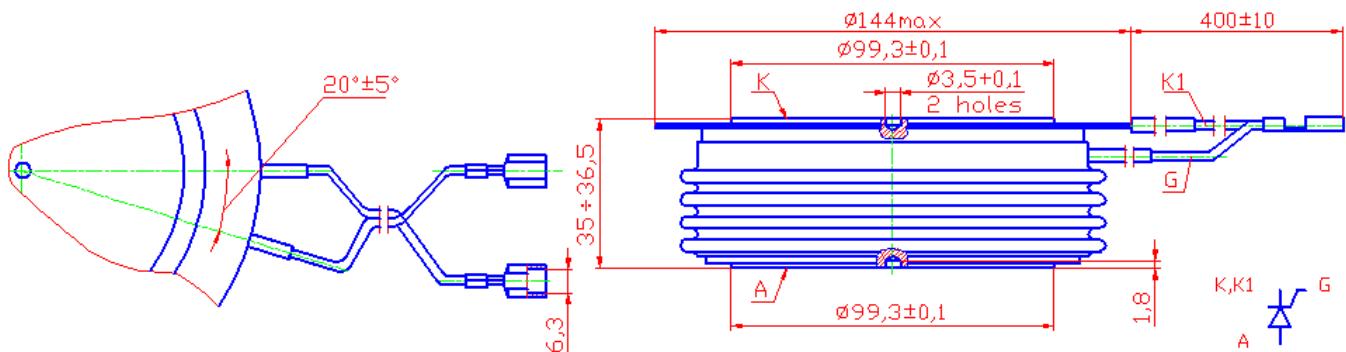
CHARACTERISTICS

U _{TM}	Peak on-state voltage	V	2,4	Tvj=25°C, I _{TM} =3,14 I _{TAV}
U _{T(TO)}	Threshold voltage	V	1,45	Tvj=125°C
R _T	On-state slope resistance	mΩ	0,125	1,57 I _{TAV} < I _T <4,71 I _{TAV}
I _{DRM} I _{RRM}	Repetitive peak off-state and reverse current	mA	200 200	Tvj=125°C, UD = U _{DRM} UR = U _{RRM}

CHARACTERISTICS				
Symbols and parameters		Units	TFI393-2500	Conditions
I _L	Latching current	A	20	T _{VJ} =25°C, U _D =12V Gate pulse : 10V, 5Ω, 1 μs rise time, 10μs
I _H	Holding current	A	1,0	T _{VJ} =25°C, U _D =12V, Gate open
UGT	Gate trigger direct voltage	V	3,0 6,0	T _{VJ} =25°C, T _{VJ} =-60°C UD=12V
IGT	Gate trigger direct current	A	0,60 1,3	T _{VJ} =25°C, T _{VJ} =-60°C
UGD	Gate non-trigger direct voltage	V	0,25	T _{VJ} =125°C, UD = 0,67 U _{DRM} Direct gate current
IGD	Gate non-trigger direct current	mA	10	
t _{gd}	Delay time	μs	2,5	T _{VJ} =25°C, UD=500V IT _M = 2500 A
t _{gt}	Turn-on time	μs	4,0	Gate pulse : 10V, 5Ω, 1 μs rise time, 10μs
t _q	Turn-off time	μs	63÷100 80÷125	T _{VJ} =125°C, IT _M =2500 A di _R /dt=10 A/μs, U _R =100V UD = 0,67 U _{DRM} du _D /dt=50 V/μs du _D /dt=200 V/μs
Q _{rr}	Recovered charge	μC	1800	T _{VJ} =125°C, IT _M =2500 A
trr	Reverse recovery time	μs	9,5	
I _{RRM}	Peak reverse recovery current	A	360	dir/dt=50 A/μs, U _R =100V
(dud/dt)crit	Critical rate of rise of off-state voltage	V/μs	500 1000	T _{VJ} =125°C, UD = 0,67 U _{DRM} Gate open
R _{thjc}	Thermal resistance junction to case	°C/W	0,0065	Direct current, double side cooled

ORDERING							
	TFI	393	2500	24	7	1	1
	1	2	3	4	5	6	7

1. Fast thyristor with interdigitated gate structure.
2. Design version.
3. Mean on-state current, A.
4. Voltage code (24=2400 V).
5. Critical rate of rise of off-state voltage (6 ≥ 500 V/μs, 7 ≥ 1000 V/μs).
6. Group of turn-off time (du_D/dt=50 V/μs, A₃ ≤ 100 μs, B₃ ≤ 80 μs, 1 ≤ 63 μs).
7. Group of turn-on time (1 ≤ 4 μs).



Mounting force : 80 ÷ 90 kN
Weight : 2800 grams